

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BYUNGHOO KANG	06/05/2014
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Property Type	Number
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NAME OF SUBMITTER:	MARY BREEN SMITH
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DATE SIGNED:	07/03/2014
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Total Attachments: 1 source=2014_07_03_Assignment_0338_59PCTUS#page1.tif
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ASSIGNMENT

WHEREAS, the undersigned inventor (referred to, collectively, if more than one, as "Assignor") has made an invention entitled **Device for Measuring Deformation of a Structure and a Method for Measuring Deformation of a Structure Using the Same**, which was described in International Patent Application PCT/KR2010/001299, filed on March 2, 2010, and in 35 U.S.C. 371 U.S. Application No. 13/203,217, now Patent No. 8,671,769;

WHEREAS, Industry-Academic Cooperation Foundation, Yonsei University and Technovalue Co., Ltd. having a place of business at Yonsei University, 134, Sinchon-dong, Seodaemun-gu, Seoul 120-743, Republic of Korea and 701, World Meridian Biz Center, 15-1, Yangpyeongdong 3-ga, Yeongdeungpo-gu, Seoul 150-103, Republic of Korea (referred to as "Assignees") desire to acquire all right, title and an equal undivided interest in and to the above identified invention and application;

NOW, THEREFORE, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, does hereby sell, assign, convey and transfer unto Assignee all right, title and interest in and to the above identified invention and application, together with all corresponding foreign applications and patents which may be filed thereon, including the right to claim priority from the above identified United States application; and Assignor hereby agrees that Assignor will sign all lawful papers, including, without limitation, all divisional, continuation, renewal, extension and reissue applications, and make all rightful oaths in execution thereof, and will generally do everything possible to aid Assignee, its successors, assigns and nominees to obtain and enforce proper protection for the invention in all countries, this obligation to be binding upon Assignor (each and severally, if more than one) and upon Assignor's personal representative or other legal successor.

IN TESTIMONY WHEREOF, the undersigned Assignor (and each of them, if more than one) has signed below.

Date: Jun 5, 2014



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